

PowerWize BMI High-Current Panel-to-Board/Busbar Interconnects are available with crimp contacts using 3.40mm (75.0A), 6.00mm (110.0A) and 8.00mm (175.0A) COEUR sockets transmitting high current through right-angle headers that can be attached to printed circuit boards or busbars



Blind-Mating Right-Angle Header



Blind-Mating
Panel-Mount Receptacle Crimp



Crimp Contact



TPA Retainer

PRODUCT FEATURES AND ADVANTAGES



..... Optimal current-carrying capacity with multiple contact beams

Provides low contact resistance, low voltage drop and minimal heat generation at the contact interface



Blind-mating guideposts

Enable the inner wall of the header shrouds to align the connectors during mating, facilitating trouble-free mating in drawer-style applications where the connectors are obscured



fabrication for applications where cable assembly lengths are uncertain until installation is underway





Self-aligning panel-mount receptacle flanges

Accept either force-fit standoffs paired with bolts (used when the assembler only has access to one side of the panel) or shoulder screws paired with nuts (often used when the assembler has access to both sides of the panel), allowing the panel mount receptacle +/- 2.00mm of radial float to mitigate tolerance stack-up issues



Shoulder Screw







Force-Fit Standoff

Bolt

Nut





Mechanical keying with unique geometry at the front of the panel-mount receptacle and matching geometry on the panel cutout

Helps ensure the receptacle is installed in the proper orientation



Mechanical keying with unique geometry at the front of the panel-mount receptacle and matching geometry on the header shroud

Helps prevent mismating between the receptacle and header



Mechanical keying with crush/locating pegs on headers

Helps ensure right-angle headers are properly oriented on printed circuit board or busbar









Screw-mount pins attached to both printed circuit boards and busbars; solder tail pins attached to printed circuit boards

Offers options to attach pins to different substrates for design and manufacturing flexibility

Crimp contacts available to accept a wide range of wire gauges (10 AWG to 1/0 AWG)

Provides design and manufacturing flexibility



Secondary substrate attachment

Achieves additional board retention (if desired) by attaching the right-angle header to the substrate using M3 bolts, nuts and the two mounting flanges molded into the body of the header



Reliable crimp geometry eight-sided crimp profile

Helps ensure minimal contact resistance at the interface between the wire and the crimp barrel, contributing to the system's minimal heat generation and higher current-carrying capacity compared to other designs





Terminal backout assurance

Provides two (opposed) positive locks that hold the TPA retainer securely to the blindmate receptacle housing silo

Helps prevent the crimp contact from backing out of the receptacle with six beams robustly holding the crimp contact inside the TPA retainer

User-friendly cable assembly build

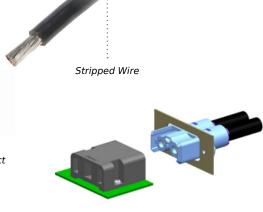
The contact is crimped to the stripped wire. The TPA retainer slips completely over the crimped contact and its beams are positioned against the rear of the contact flange.

The subassembly is then inserted into one of the panel mount housing silos with the TPA retainer locking into place and generating mechanical feedback and an audible click to help ensure the crimped lead contact is fully engaged and minimizes the opportunity for terminal backout.





TPA Retainer



MARKETS AND APPLICATIONS

Telecommunications/Networking

Servers
Data storage units
Power distribution units (PDUs)
Uninterruptible power supplies
Digital cross-connect switches
Network routers

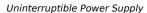
Data Centers

Enterprise switches
Servers
Data storage units
Power shelves
Power distribution units (PDUs)
Uninterruptible power supplies
Environmental control equipment



Inverters







Data Center Servers



SPECIFICATIONS

REFERENCE INFORMATION

Packaging: Headers and TPA Retainers – Tray
Panel Mount Receptacle Housing – Bag
Crimp Contacts – Vacuum Pack Bag
see Packaging Specification for more details
Use With: Printed Circuit Boards and Busbars
Designed In: Millimeters
RoHS: Yes

PHYSICAL

Panel Mount Receptacle Housing: PBT (Black)
TPA Retainer: PBT (Black)
Header Housing: LCP (Black)
Contact: High–performance Copper (Cu) Alloy
Plating:

Socket Contact Area - Gold (Au)
Header Pin - Silver (Ag)
PCB Thickness (min.): 1.60mm
Busbar Thickness (min.): 1.50mm
Operating Temperatures: -40 to +125°C

3.40MM SIZE ELECTRICAL

Current (max.): 75.0A Contact Resistance (max.): 0.25 milliohms

MECHANICAL

Voltage (max.): 400.0V

Whole connector Mating Force (max.): 45.0N Whole connector Unmating Force (min.): 10.0N Durability (min.): 200 mating cycles

6.00MM SIZE ELECTRICAL

Voltage (max.): 600.0V Current (max.): 110.0A

Contact Resistance (max.): 0.1 milliohms

MECHANICAL

Whole connector Mating Force (max.): 60.0N Whole connector Unmating Force (min.): 12.0N Durability (min.): 200 mating cycles

8.00MM SIZE ELECTRICAL

Voltage (max.): 1,000.0V Current (max.): 175.0A

Contact Resistance (max.): 0.1 milliohms

MECHANICAL

Whole connector Mating Force (max.): 70.0N Whole connector Unmating Force (min.): 20.0N Durability (min.): 200 mating cycles

www.molex.com/link/powerwizebmi.html